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(54) **METHOD FOR INJECTION COMPRESSION MOLDING OF CONDUCTIVE THERMOPLASTIC RESIN COMPOSITION**

(57) An injection/compression molding method comprising the steps of: a injection filling step for injection filling a conductive thermoplastic resin composition containing a conductive filler at a ratio of 70 to 95 mass% into a cavity space 13 with the interval in the range of 0.5 to 5.0 mm formed by mating faces 11a, 12a of dies 11, 12 each having a temperature in the range of 150 to 250 °C; and a compression forming step for compression forming, after the filling step is finished and the die space was closed, the conductive thermoplastic resin composition filled in said space at the compression speed in the range of 1.0 to 20 mm/sec with the compression pressure of 10 MPa or higher. As obtained molded product contains the conductive filler homogeneously distributed at a high content ratio, so that the molded product can be applied to, for instance, a separator for a fuel cell.

FIG. 1

